



# The webinar will begin shortly...

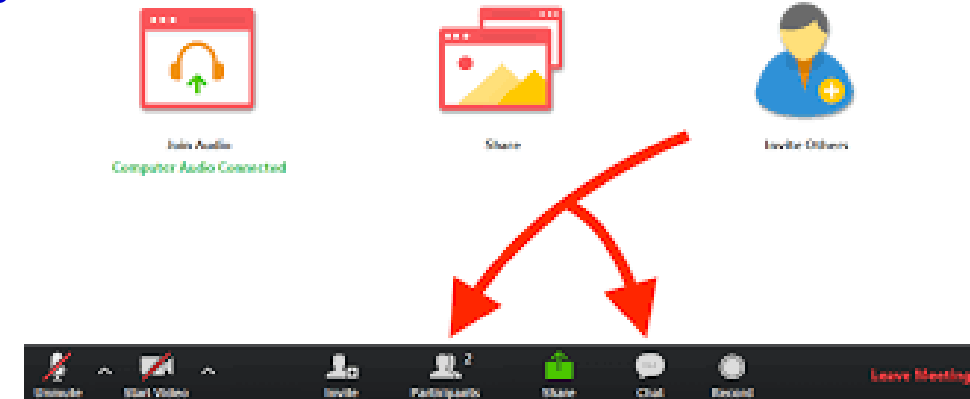
**IF YOU HAVE NOT SIGNED IN WITH YOUR FULL NAME & COMPANY, PLEASE DO SO  
YOU CAN “RENAME” YOURSELF IN THE “PARTICIPANTS” TAB**

**IF YOU DO NOT INCLUDE YOUR NAME AND COMPANY  
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# Welcome to Webinar Wednesday!

## HOUSEKEEPING:

- Make sure you **SIGN IN** with your **FULL NAME & COMPANY**, as we may need it to unmute you and bring you into the discussion (If you do not include your name and company, you may be ejected from the call!)
- You can “rename” yourself in the “**participants**” tab
- Questions can be asked by either:
  - Clicking the “**Participants**” tab and then “**Raise hand**”
  - Click the “**Chat**” tab and use text box to ask a question
  - you can direct this privately to me or to everyone
- The **PRESENTATION PDF** and **RECORDING** of this webinar will be available for download to members from the IWPC research library at [www.iwpc.org](http://www.iwpc.org)



# IWPC Webinars & Workshops H2 2021

**Aug 18:** Building The 5G Network Of The Future



**Aug 25:** Antenna in Package for 5G mmWave Infrastructure



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**Dec 15:** Concept Design, Functional Prototyping, Engineering Design Development, Certified 3rd Party Environmental and Mechanical Testing, Verification and Design Validation



# Building the 5G Network of the Future



**Eric Westberg – Director, Product Management**



**Yash Suvarna – Portfolio Manager**



**Duco Das – Portfolio Manager**



**18 AUGUST 2021**



**SECURE CONNECTIONS  
FOR A SMARTER WORLD**

**PUBLIC**

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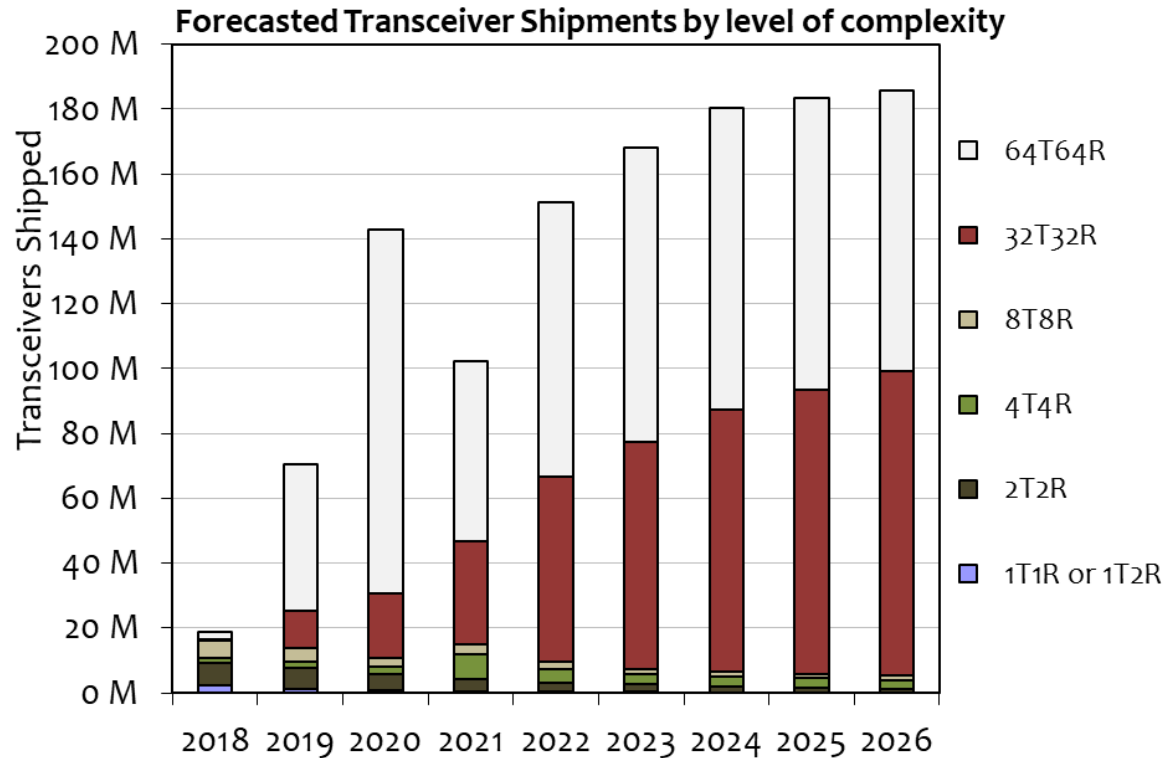


# Agenda

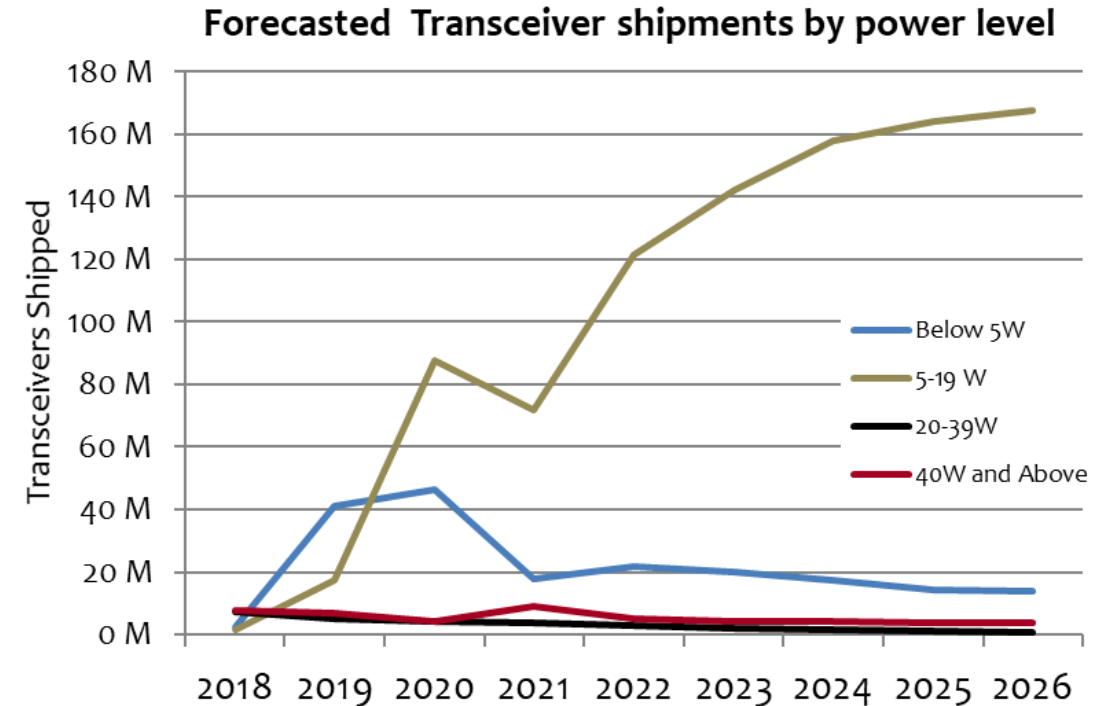
1. Market Insights
2. Technology and Radio Unit Challenges
3. Sub 6-GHz
4. mmWave

# LATEST 5G MARKET DEVELOPMENTS

Mobile Experts, May 2021

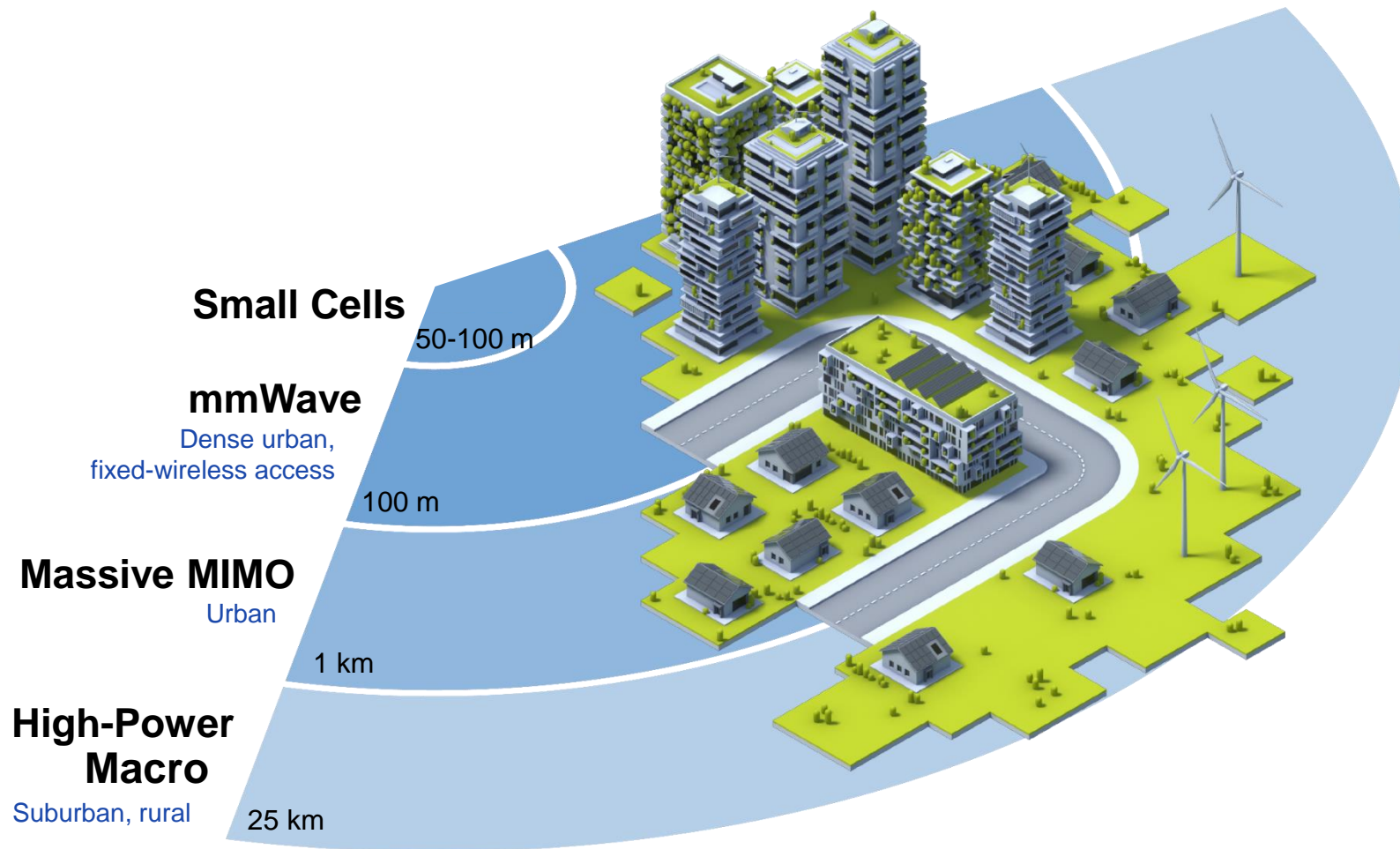


Transmit and Receiver lineups will grow significantly due to Massive-MIMO deployments for both sub-6 GHz and mmWave.



Due to increased number of transmit and receive per radio we will see more of 5-19W PA's shipped over next few years. mmWave (higher frequencies, lower powers) will be added on top as a non-standalone layer in the network

# 5G IS A DIVERSE AND COMPLEMENTARY NETWORK ECOSYSTEM

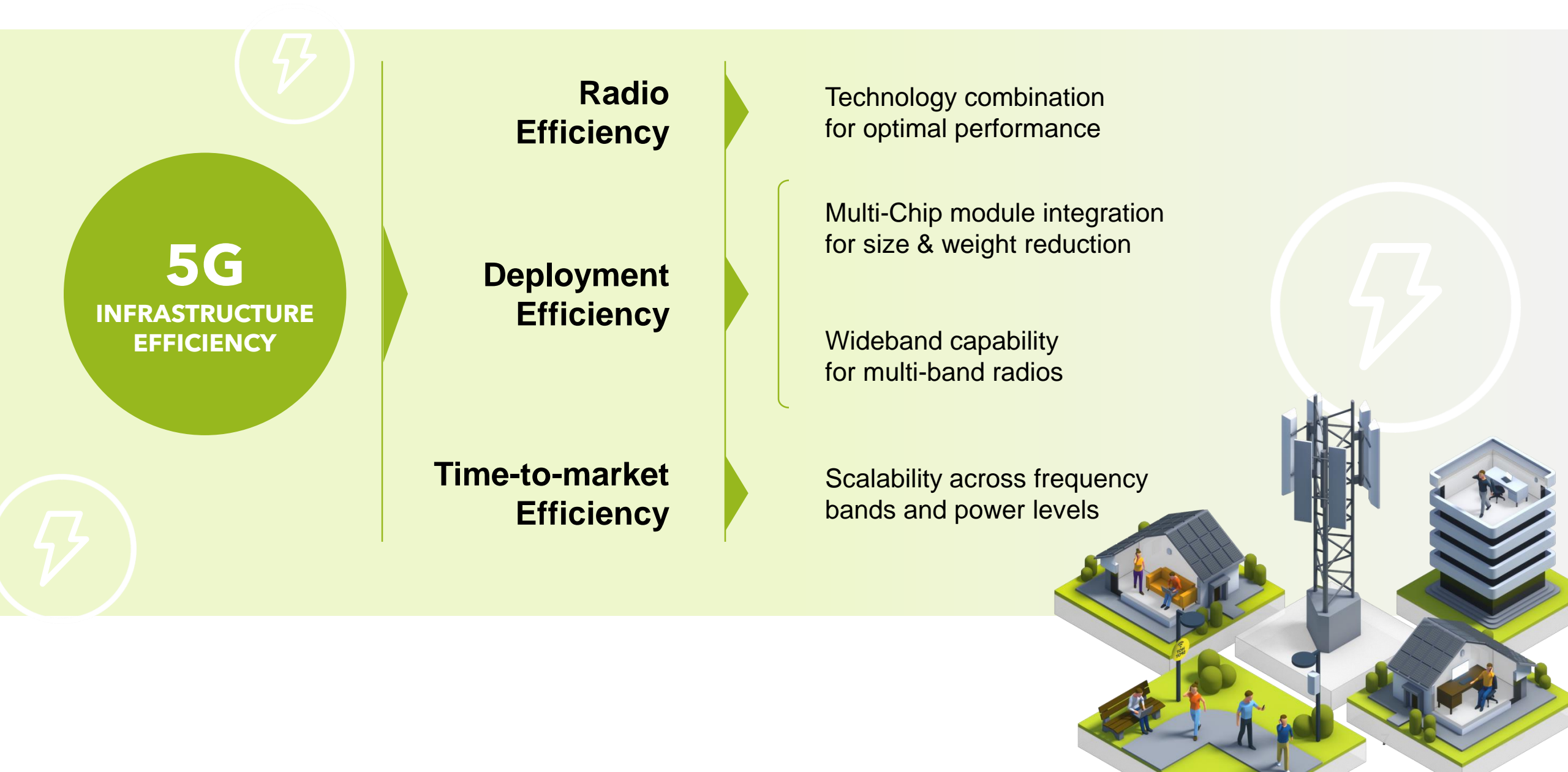


**MULTIPLE NETWORK ARCHITECTURES  
RAPIDLY EVOLVING DEPLOYMENTS**

## Key Challenges:

- Frequencies
- Power levels
- Architectures

# ACCELERATING 5G ENERGY EFFICIENCY



## 5G INFRASTRUCTURE EFFICIENCY

### Radio Efficiency

Technology combination  
for optimal performance

### Deployment Efficiency

Multi-Chip module integration  
for size & weight reduction

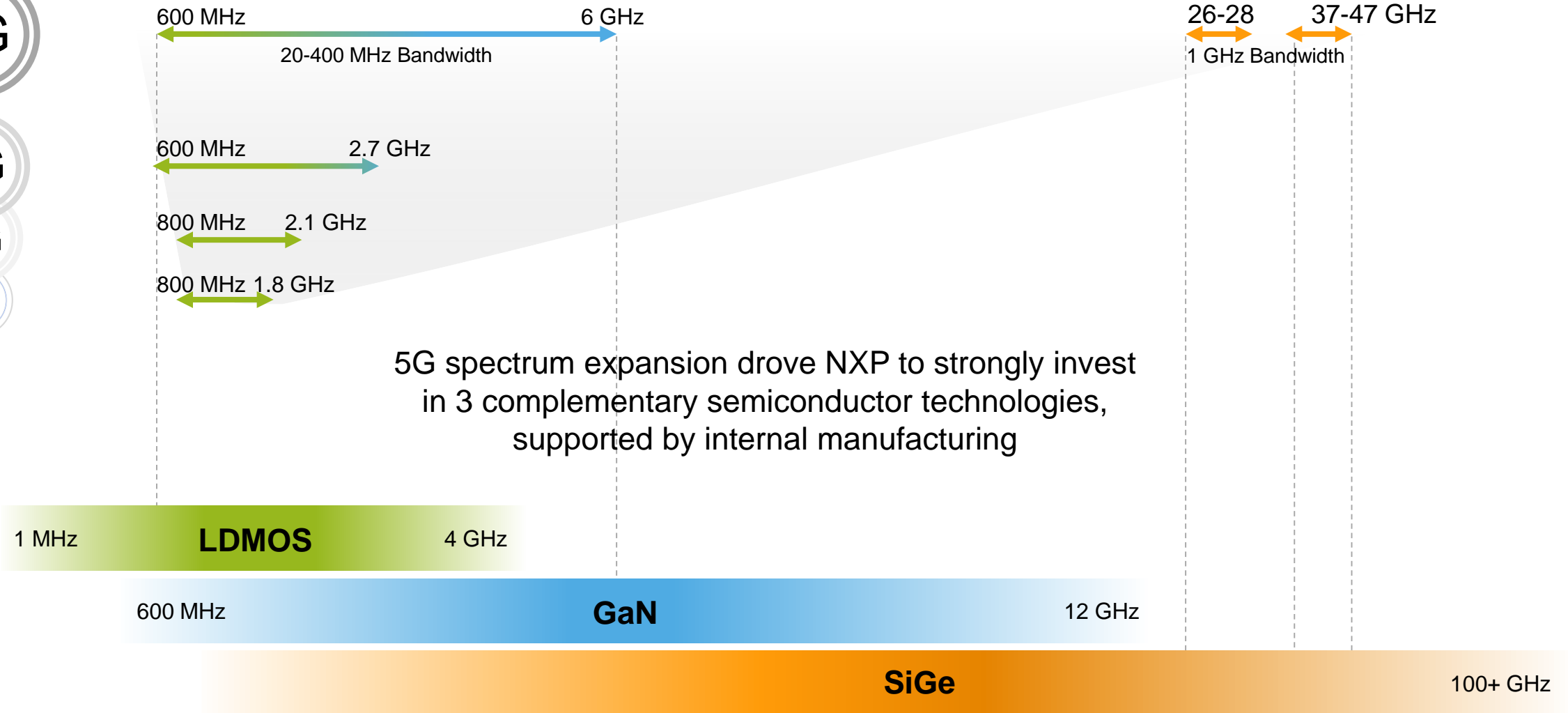
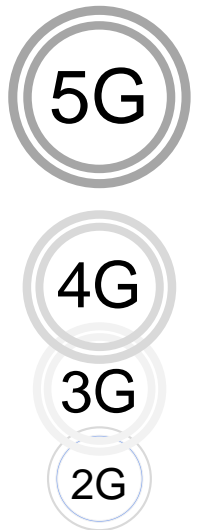
Wideband capability  
for multi-band radios

### Time-to-market Efficiency

Scalability across frequency  
bands and power levels

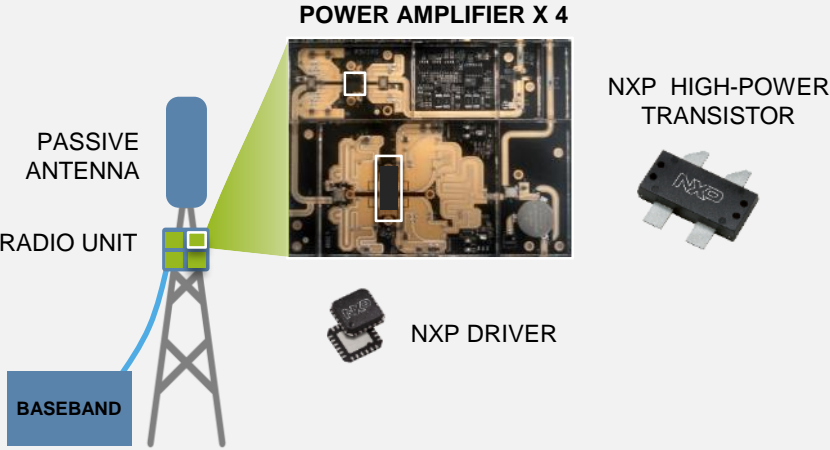


# KEY TECHNOLOGIES TO ENABLE 5G RF POWER



# RADIO UNIT RF FRONT-END

## High-power Macro



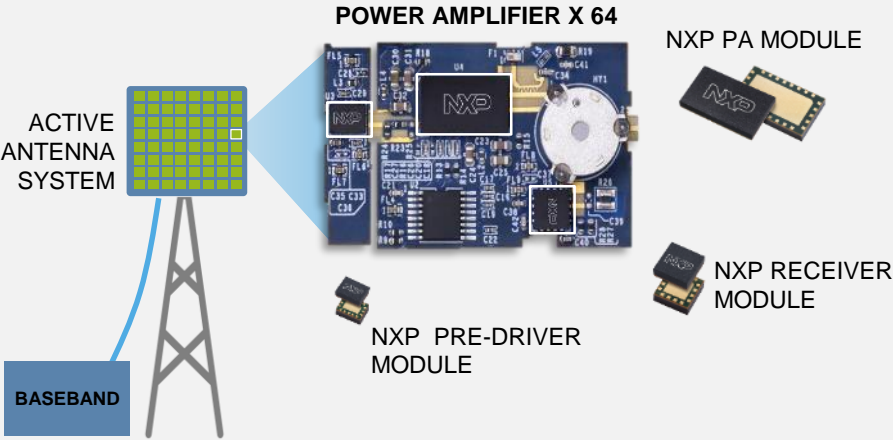
4T4R

4 X 40 W

8T8R

8 X 40 W

## Massive MIMO



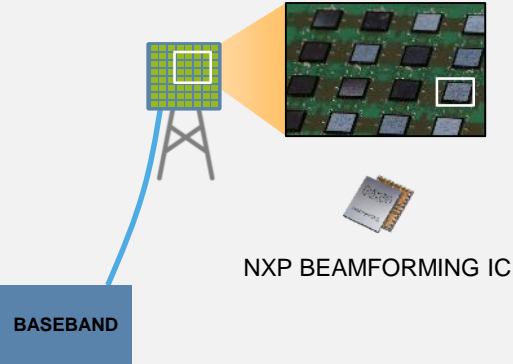
32T32R

32 X 10 W

64T64R

64 X 5 W

## mmWave



mmWave

256 X 200 mW

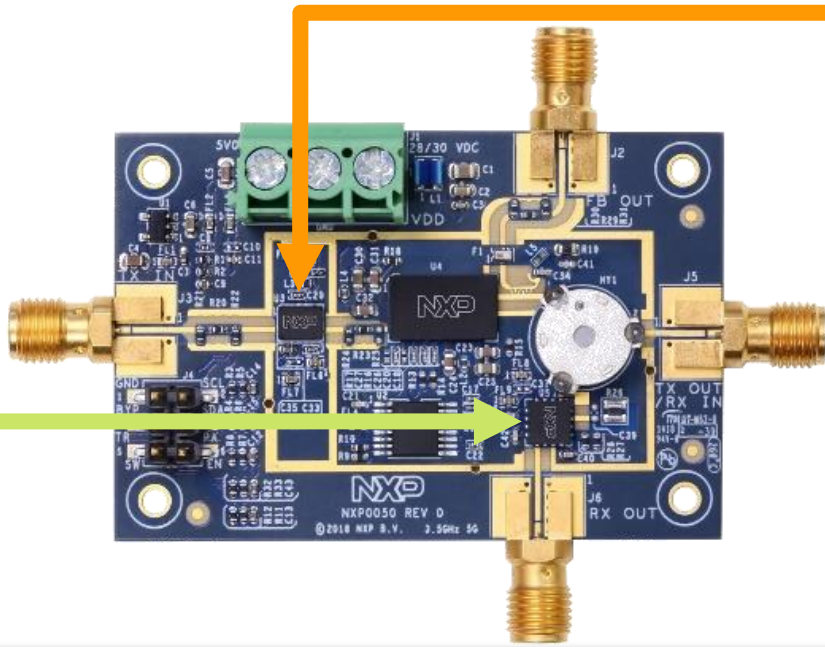
Coverage (lowest cost / km<sup>2</sup>)

Capacity (lowest cost / Gb/s)

NXP Addressing all deployment options

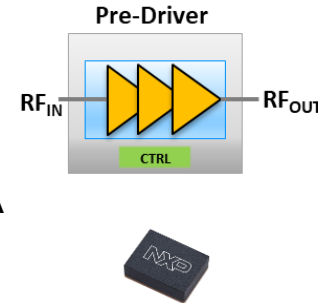
+ **Small Cells:** macro-like architecture at low-power level

# PRE-DRIVER AND RECEIVER



## Pre-Driver Amplifier Module

- GaAs or SiGe technology
- Typically, 2-3 stage design
- Operated at 12-14dB OBO
- Higher Gain to drive final PA
- High linearity
- Wide RF Bandwidth
- 50  $\Omega$  in/out with pin-to-pin compatibility

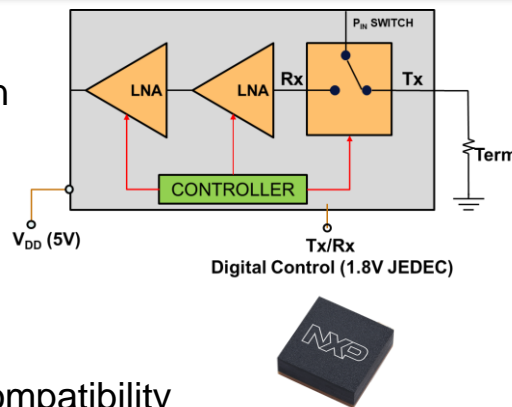


## NXP Pre-Driver Product Example:

- 50 Ohm in/out
- SiGe Technology
- 3 x 3 QFN package
- Frequency 2300 to 4200 MHz
- Gain 30.5dB
- Psat 28 dBm
- ACLR -46dBc
- 95mA Icc

## Rx Front-End Module

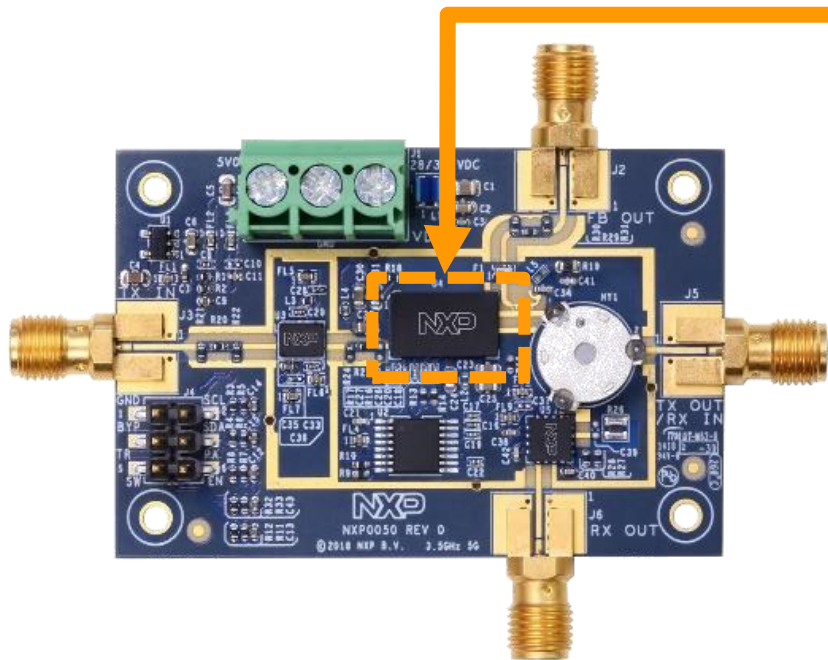
- GaAs or SiGe Technology
- Switch + 2 stage LNA design
- Lowest NF <1dB
- Higher gain design
- High isolation
- Low power consumption
- 50  $\Omega$  in/out with pin-to-pin compatibility



## NXP RX FEM Product Example:

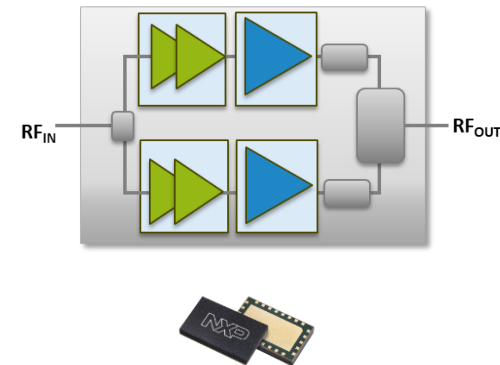
- 50 Ohm in/out
- SiGe Technology
- 5 x 5 QFN package
- Frequency 3300 to 4200 MHz
- Gain 36dB
- 37dBm TX power handling (9dB PAPR)
- Noise Figure 1.3dB
- 170mW P<sub>diss</sub> per channel

# POWER AMPLIFIER



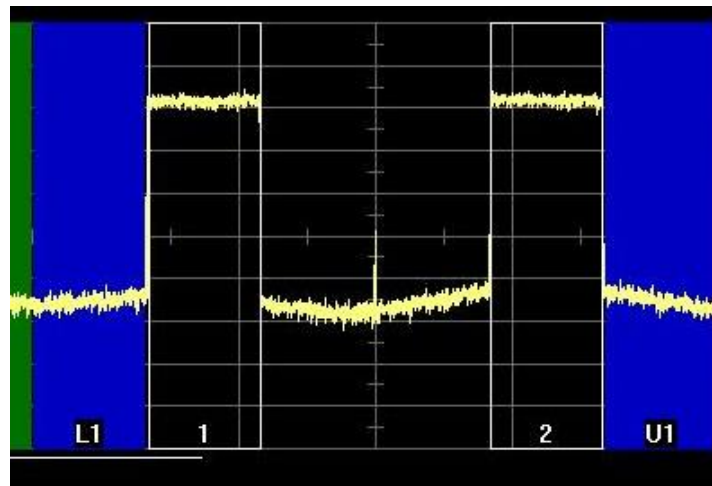
## Power Amplifier Module

- LDMOS or GaN technology
- Doherty power amplifier
- Operated at 8-9dB OBO
- High linearized efficiency
- Wide RF Bandwidth and iBW
- Reduced size
- Thermal management
- 50  $\Omega$  in/out with pin-to-pin compatibility across frequency and power



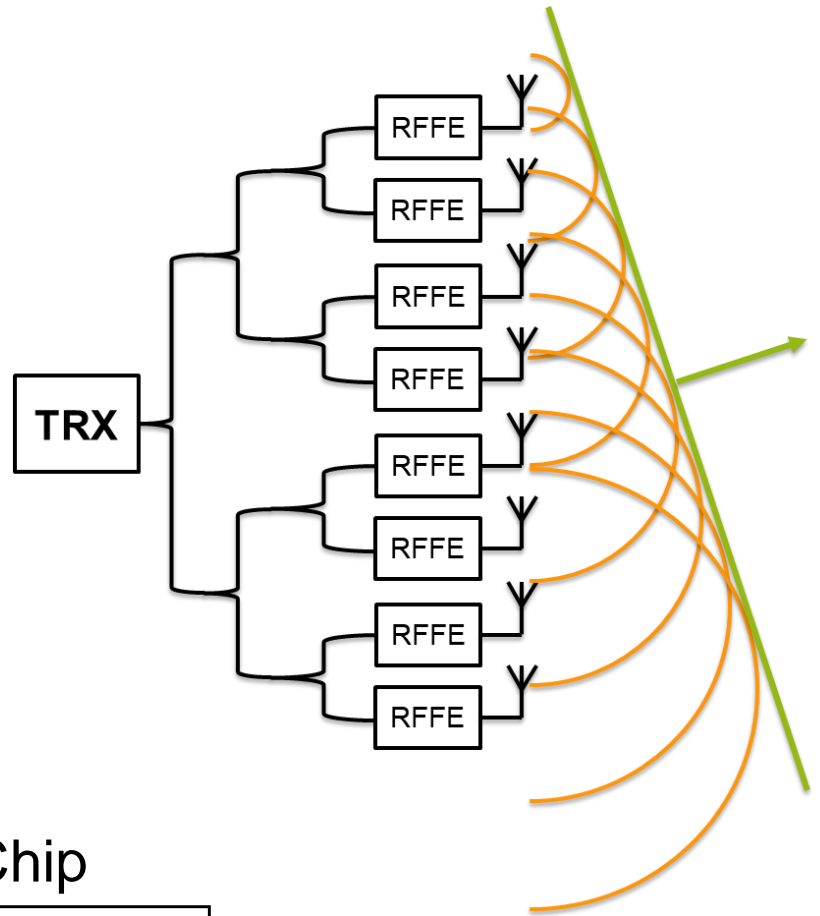
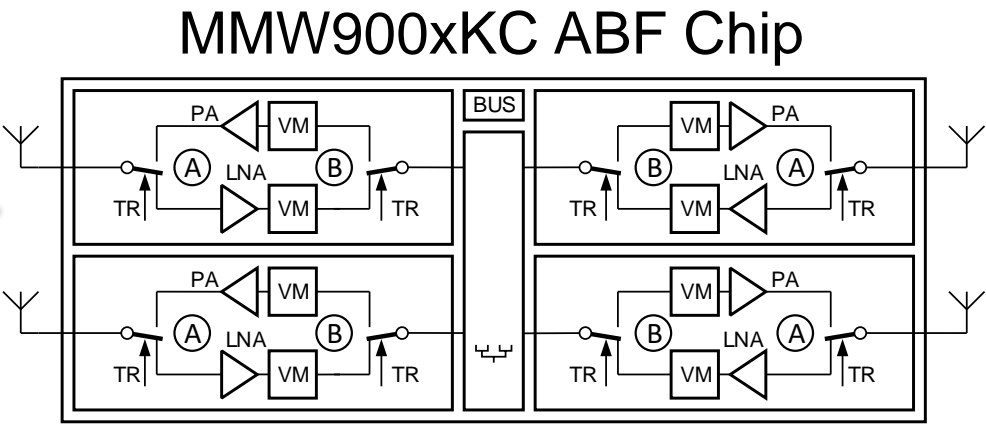
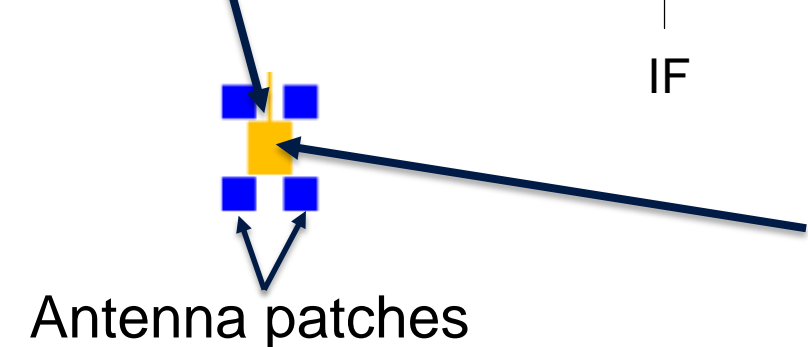
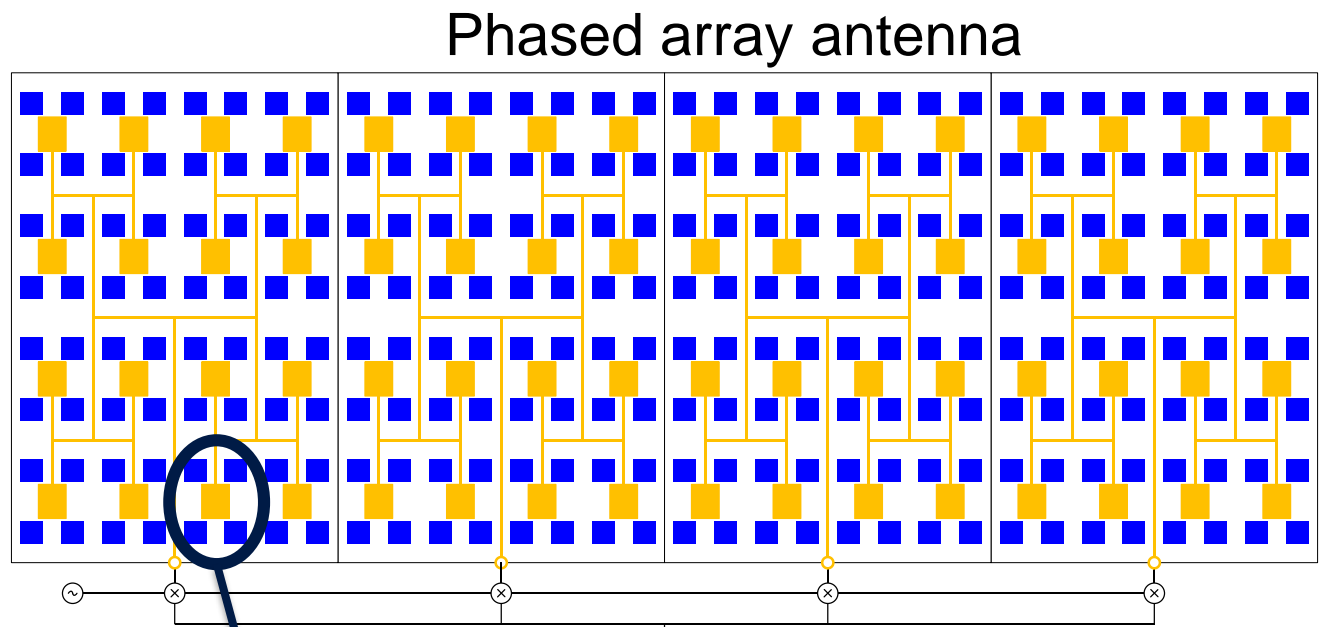
### NXP Product Example:

- 50ohm in/out Integrated Doherty
- 5V LDMOS driving 48V GaN final stage
- 10 x 6 LGA over-molded plastic package
- Frequency 3400 to 3800 MHz
- $P_{avg} = 39.5$  dBm
- $P_{5dB} = 48$  dBm
- Gain > 32dB
- PAE > 46%
- iBW = 400MHz



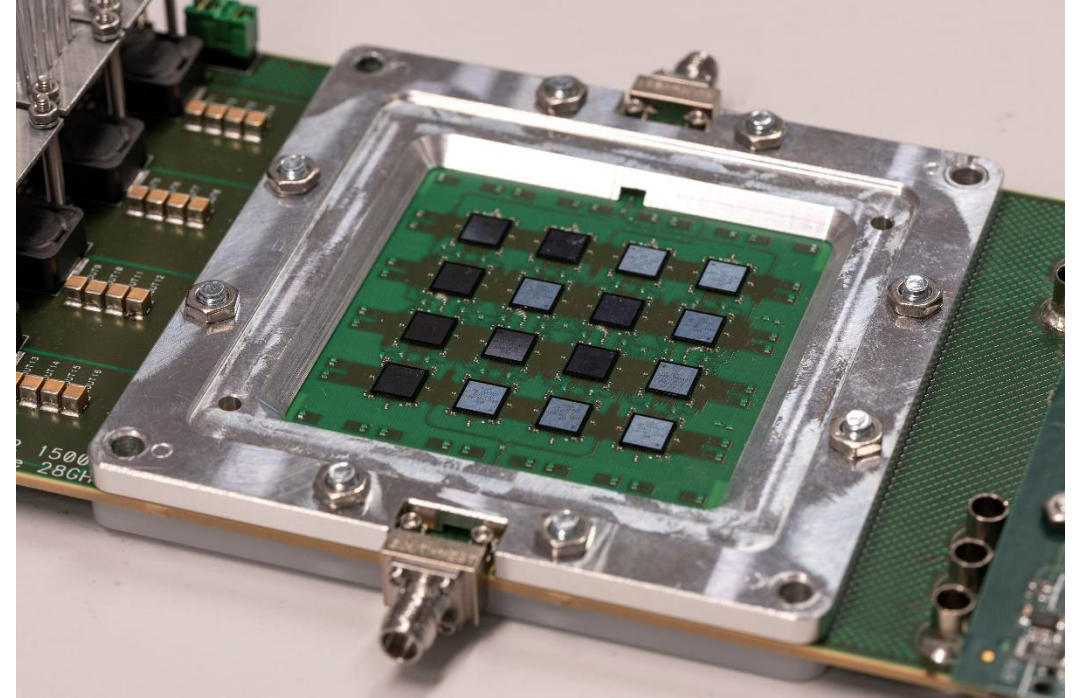
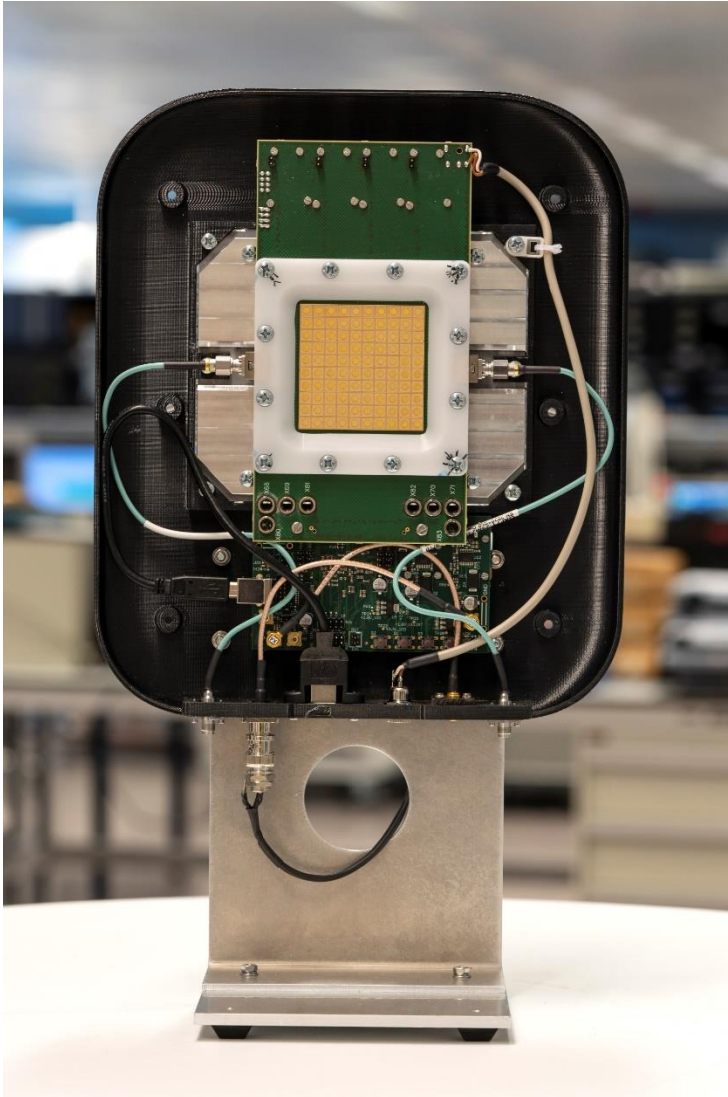
Center Freq = 3.6 GHz,  
Carrier BW = 100MHz,  
Channel Spacing = 200MHz,  
 $P_{avg} = 39.5$  dBm

# ANALOG BEAM FORMER ICS FOR MMWAVE PHASED ARRAYS





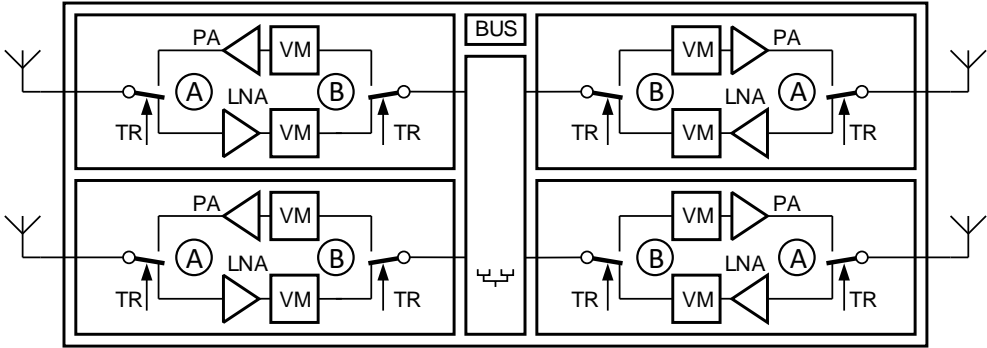
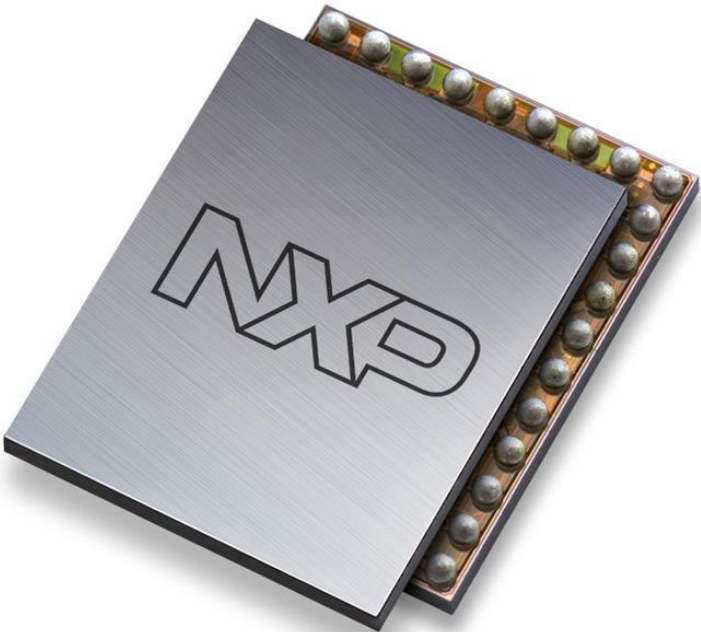
## ANTENNA DEMO / REFERENCE DESIGN KIT



- System development kit to support system co-design and evaluate BFICs at antenna level
- Full demo kit with 8x8 antenna panel, control board with GUI and power supplies included

# 28 GHZ MMW9002KC ANALOG BEAMFORMER

Features and Benefits		
TX	Pdiss	400 mW per channel
	P1dB	19 dBm
	EVM	< 2% at 8 dBm
	Power Gain	27 dB
RX	Pdiss	0.35 W per channel
	Power Gain	22 dB
	Noise Figure	6 dB
Digital	High-speed SPI interface	
Diagnostics	Temperature sensor and power detectors on all antenna ports	
Package	4.39 x 3.59 x 0.5 mm WLCSP	



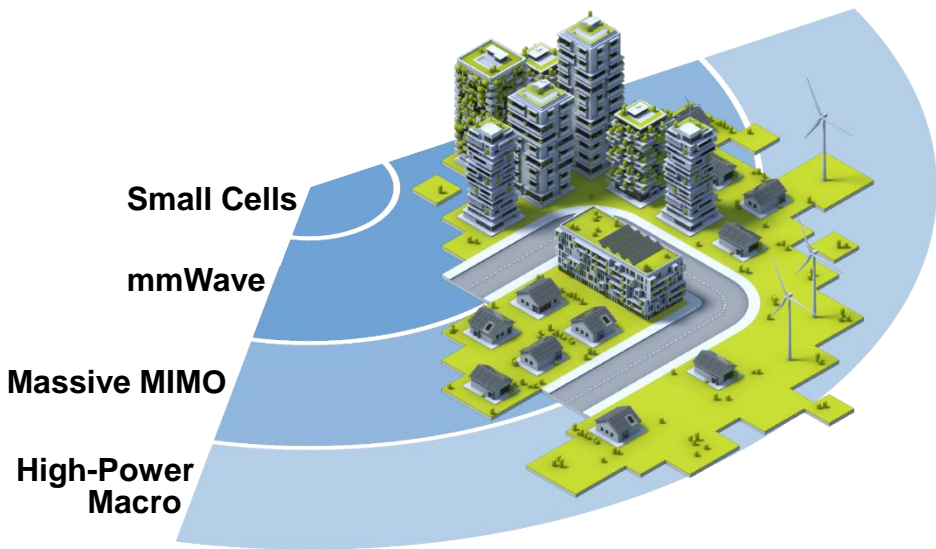
CONCLUSION: JOURNEY TO 5G

From:

To:



2-3-4G



5G

NXP enables the diversification of 5G Radio Access Networks

NXP SERVES ALL 5G CONFIGURATIONS

- Frequencies
- Power levels
- Architectures



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